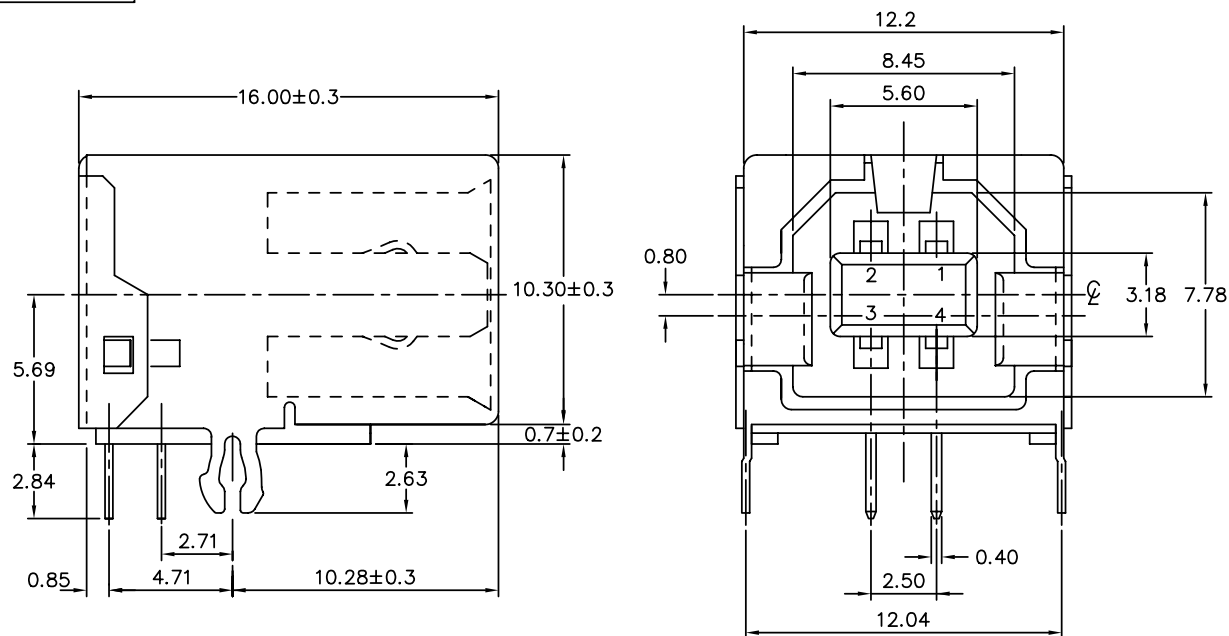
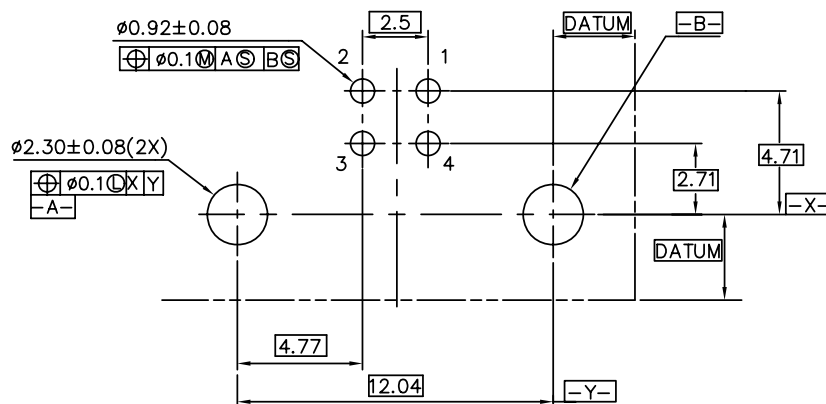


61729-*



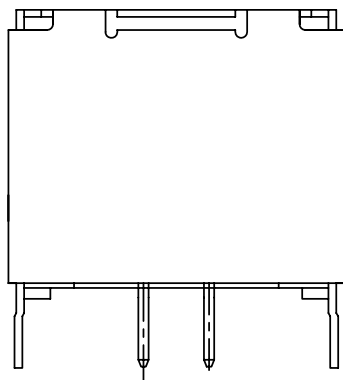
61729 - X X X X X P S LF

LEAD FREE OPTION

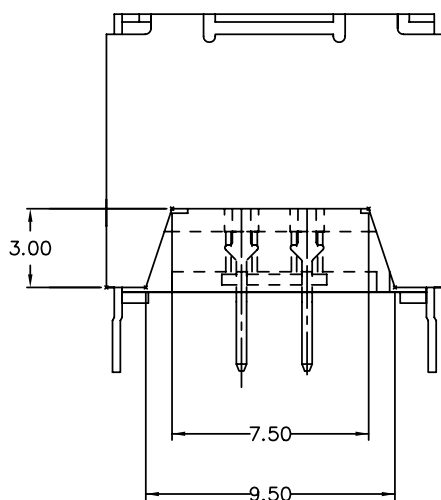


P.C. BOARD LAYOUT

mat'l. code				surface ISO 1301 ✓		tolerance ISO 406 ISO 1101		projection 		product family USB2.0			
ltr ecn nodr date				tolerances unless otherw		wise specified		title					
S N05-0242 PH 08/22/05				angle ungrad		0.0±0.3				USB RECEPTACLE B TYPE			
T N06-0103 HB 04/15/06						0.00±0.20							
U N08-0238 R,B 11/3/08						0.000±0.10							
				0'±2'				scale 4:1					
V N08-0264 R,B 12/08/08				dr LQ.LEI		2013-12-17				dwg no		sheet 1 of 2	size
W EDR-ELX-A-1653 LQ 12/17/13				enrg LQ.LEI		2013-12-17				61729		A4	
				chr RICK BIAN		2013-12-17							
				appd RICK BIAN		2013-12-17				type Product Customer Drawing			
sheet index		revision		sheet 1-2									



TYPE "1" FULL BACK



TYPE "2" PARTIAL BACK

NOTES:

1. MATERIAL:
SHIELD & CONTACTS: COPPER ALLOY
HOUSING: UL 94V-0 ,HIGHT TEMPERATURE THERMOPLASTIC.
COLOR: SEE PRODUCT NUMBER CODE.
2. PLATING: SEE PRODUCT NUMBER CODE.
SHIELD: BRIGHT TIN
NICKEL UNDERPLATE.
3. DATUMS & BASIC DIMENSIONS TO BE DETERMINED BY CUSTOMER
4. RECOMMENDED BOARD THICKNESS IS 1.57 mm (.062)
5. PACKING STANDARD GS-14-920 WILL BE APPLIED FOR LEAD FREE P/N'S
6. FOR LEAD FREE P/N, THE PRODUCT MEET EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATION AS DESCRIBED IN GS-22-008
7. FOR LEAD FREE P/N'S, THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRO-RED OR VAPOR PHASE REFLOW OVEN.
8. THE PART CAN BE USED FOR PIP PROCESS.

mat'l. code	surface ISO 1301 ✓	tolerance ISO 406 ISO 1101	projection mm	product family USB2.0
ltn ecn nodr date	tolerances unless otherwise specified	0.0±0.3	mm	title USB RECEPTACLE B TYPE
- - -	angle 0°±2'	0.00±0.20	scale 4:1	
	dr LQ.LEI 2013-12-10	0.000±0.10		dwg no 61729
	enr LQ.LEI 2013-12-10			sheet 2 of 2
	chr RICK BIAN 2013-12-10			size A4
	appd RICK BIAN 2013-12-17			type Product Customer Drawing
sheet index	revision sheet -			